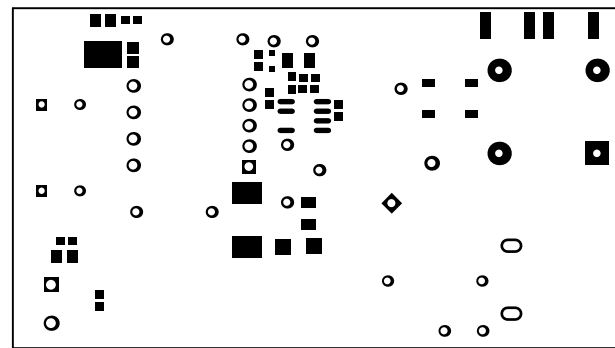
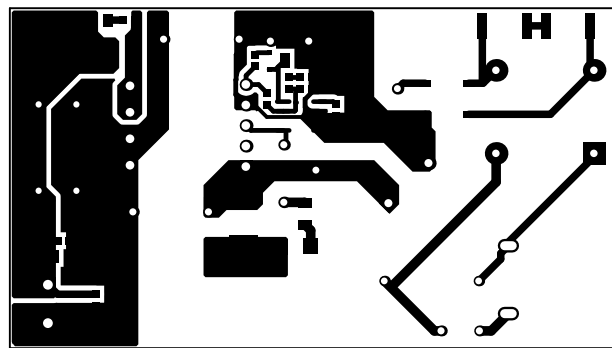


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10467	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 10/30/2014 9:08:15 AM	TEXAS INSTRUMENTS	

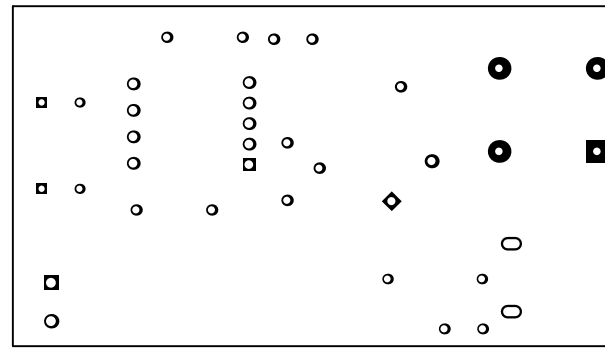
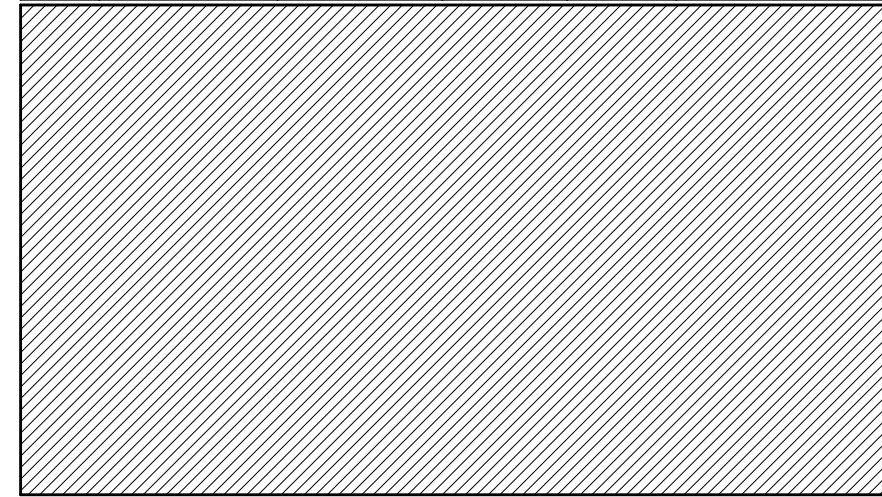


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10467	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 10/30/2014 9:08:15 AM	TEXAS INSTRUMENTS	

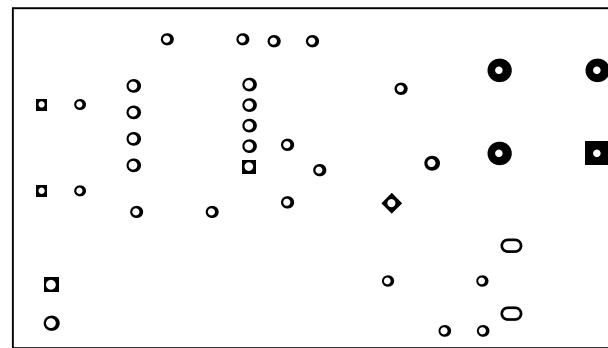


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10467	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 10/30/2014 9:08:16 AM	TEXAS INSTRUMENTS	

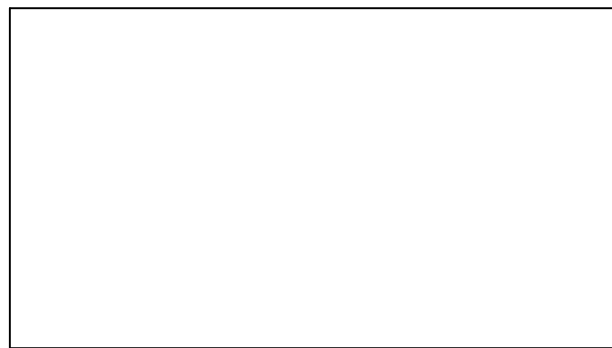
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	CAF-1	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



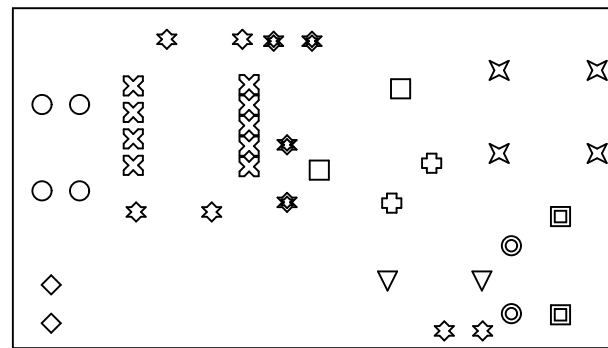
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10467	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 10/30/2014 9:08:17 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10467	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 10/30/2014 9:08:17 AM	TEXAS INSTRUMENTS	

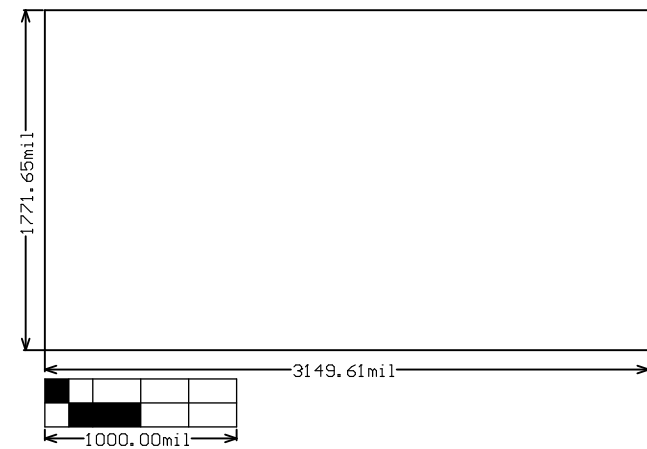


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10467	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 10/30/2014 9:08:18 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
■	2	118.11mil (3.000mm)	NPTH	Round
○	4	33.46mil (0.850mm)	PTH	Round
▽	2	35.43mil (0.900mm)	PTH	Round
□	2	37.00mil (0.940mm)	PTH	Round
☆	6	37.40mil (0.950mm)	PTH	Round
✱	4	38.00mil (0.965mm)	PTH	Round
⊗	4	40.00mil (1.016mm)	PTH	Round
⊙	2	43.31mil (1.100mm)	PTH	Round
⊗	9	46.06mil (1.170mm)	PTH	Round
◇	2	51.18mil (1.300mm)	PTH	Round
●	2	47.24mil (1.200mm)	PTH	Slot
	39 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10467	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 10/30/2014 9:08:18 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10467	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 10/30/2014 9:08:19 AM	TEXAS INSTRUMENTS	

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